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Pomogailo, S.I. / Shilov, G.V. / Ershova, V.A. / Virovets, A.V. / Pogrebnyak, V.M. / Podberezskaya, N.V. / Golovin, A.V. / (...) / Pomogailo, A.D., *Journal of Organometallic Chemistry*, Oct 2005
...capable to producing an activation of N-allylic substrates resulted in their double-bond [1,2]-migration and simultaneous **intra-substrate** hydrogen transfer[2]. While the catalytic properties of the mentioned complexes, in particular in alkene's oxidation...
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Xin-Ling Ma / Wei Yang, *Nanotechnology*, Nov 2003
...unit vector with direction from tip sphere centre K to substrate atom i. Functions $VI(r_{ij})$ and $VE(r_{iK})$ are the **intra-substrate** and interfacial atomic potentials, respectively. Numerical integration of equation (1) was accomplished via a leap-frog...
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MORRISON, Christopher, S. / NUVO HOLDINGS, L.L.C., *PATENT COOPERATION TREATY APPLICATION*, Sep 2005
...middle substrate 38. An opening wall 52 surrounds opening 46 and extends between bottom and top surfaces 48 and 50. An **intra-substrate** conductor 54 resides on opening

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AGHABABAZADEH, Majid / ESTABIL, Jose, J. / PAKDAMAN, Nadar / STEINBRUECK, Gary, L. / VICKERS, James, S. / TAU-METRIX, INC., PATENT COOPERATION TREATY APPLICATION, Mar 2005

...the wafer scribe area, adjacent to the **active** portion of the chips.

[0006]...exclude the scribe area adjacent to the chip **active** area.

[0007] Still further...little information on components in the **active** area chip areas of the wafer. For example...

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(May 2004) Sagar Suresh Sabade, B.E., Pune University, India; M.Tech., Indian Institute of Science, Bangalore, India Chair of Advisory Committee: Dr.

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Oct 1996
...manufacturing (Paper #: 2874-01) * Inter- and **intra-die** polysilicon critical dimension variation...practice. !23 Paper #: 2874-02 Inter- and **intra-die** polysilicon critical dimension variation...the relative range and distribution of **intra-die**, or die-level, polysilicon critical dimension...
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Microelectronics Reliability, Jan 1983
...discussed in Part II. Thermosonic gold **wire bonding** to copper conductors. VERNON A...hybrid microcircuitry requires that **wire bonding** to their surfaces be demonstrated...of critical layers. Excellent **intra-die** overlay match is demonstrated...
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KNIGHT, Thomas, F. / SALZMAN, David, B. / KNIGHT, Thomas, F., PATENT COOPERATION TREATY APPLICATION, Jan 1995
...flip-chip, tape automatic bonding (TAB), or **wire-bonding**. In the MCM-C technologies,

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ter Brake, H.J.M. / Buchholz, F.Im. / Burnell, G. / Claeson, T. / Crete, D. / Febvre, P. / Gerritsma, G.J. / (...) / Ivanov, Z., Physica C: Superconductivity and its applications, Jun 2006

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Buchholz, F.-I. / Balashov, D. / Khabipov, M.I. / Hagedorn, D. / Dolata, R. / Popel, R. / Niemeyer, J., Physica C, Feb 2001

...layer enabling contacts of the Nb top **wiring** to the junction top electrode (central...characteristics (hysteresis: less than 7%), the **intra-wafer** parameter spread for j C is below...small contact holes and connecting a **wiring** layer within these holes without...

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D Balashov / M I Khabipov / F-Im Buchholz / W Kessel / J

Niemeyer, *Superconductor Science and Technology*, Nov 1999

...corresponding to LS = 0.94 pH (**wiring**-ground), 0.71 pH (**wiring**-base) and 0.58 pH (base-ground) with **intrawafer** margins of LS = $\pm 0...$ different types of **wiring** connection (see section...less than 10%) the **intrawafer** parameter spread is...

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...time extended past the nominal endpoint to compensate for: **intrawafer**-nonuniform etch rates nonuniform film thickness Typical over-etch...investigated for low- permittivity dielectrics for interconnect **wiring**. In polymerizing environments with heavy sidewall passivation...

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Microelectronics Reliability, Jul 1993

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